

Qualification Results Summary for Copper Wire in LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	Result
Temperature/Humidity/Bias (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	PASS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020